



LOGICPIR

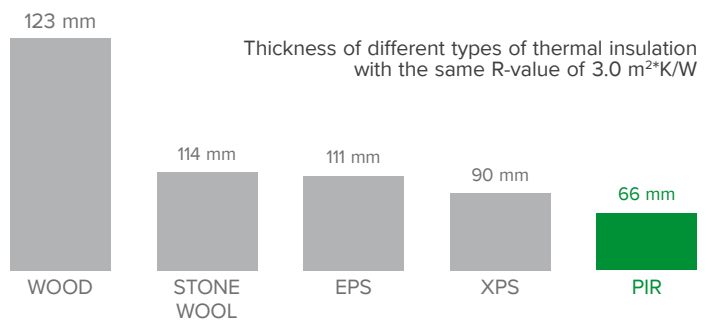
THERMAL INSULATION BOARD

LOGICPIR is an innovative thermal insulation board made of PIR (Polyisocyanurate), which is used in flat and pitched roofing systems, basements, floors and facades. Being very rigid and perfectly flat, LOGICPIR is an ideal substrate for roofing materials. LOGICPIR has high compressive strength and a very low thermal conductivity value of $0.022 \text{ W/m}^{\circ}\text{K}$.

More than 95% of PIR consists of closed cells. PIR board does not absorb water and does not burn. It maintains stable parameters for a long period of time.

TECHNICAL DATA

PROPERTIES	PERFORMANCE
Thickness, mm	20-100 (increments 10 mm)
Board sizes, mm	1200x600, 2400x1200
Thermal conductivity, $\text{W/m}^{\circ}\text{K}$	0.022
Reaction to fire	Class E
Compressive strength, kPa	120
Long term water absorbance, %	1
Surface type	Aluminium foil or glass fibre mat



LOGICPIR
with aluminium surface



LOGICPIR
with glass fibre mat surface

UNIQUE FEATURES OF LOGICPIR



RELIABILITY AND DURABILITY

Throughout its 25-year service life, LOGICPIR retains its qualities. It functions effectively within a temperature range from -65°C to +110°C (suitable for any climate).



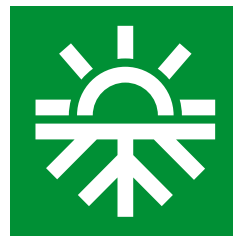
DOES NOT BURN

LOGICPIR is a non-flammable material. When in contact with an open flame, polymer burns on the surface only. This creates a charcoal skin, which is an effective defence against further polymer damaging.



DYNAMIC LOAD RESISTANCE

LOGICPIR complies with class 2 for the dynamic load (EN 826). Compression strength of 120 kPa provides high resistance against deformation due to operation loads.



RECORD LOW THERMAL CONDUCTIVITY

LOGICPIR has a very low thermal conductivity of 0.022 W/m*K. Boards have L-shaped edges, so they fit tightly together and thus prevent cold bridges.



LOW DENSITY

Use of LOGICPIR reduces the overall weight of the construction. This is especially important for roofs renovation. Transportation costs are substantially reduced as well.

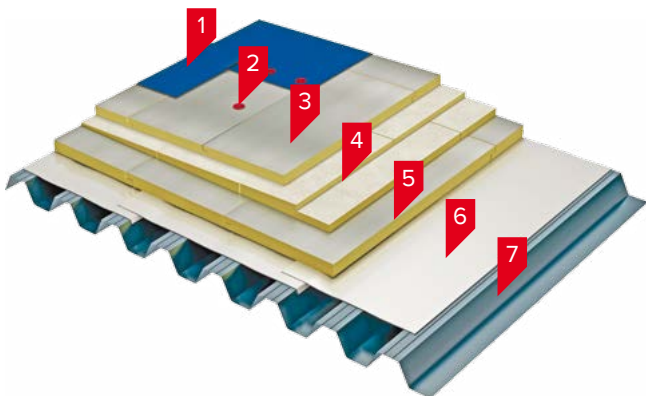


DOES NOT ABSORB WATER

The board structure consists of closed rigid cells, which do not allow water to come into the material. Composite facers provide an additional vapor barrier.

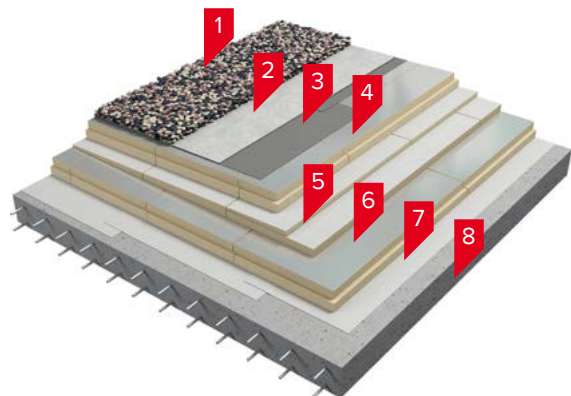
ROOFING SYSTEMS

MECHANICALLY FIXED ROOFING SYSTEM



1. PVC membrane LOGICROOF V-RP
2. Mechanical fixation
3. Thermal insulation board LOGICPIR
4. Thermal insulation board LOGICPIR Slope
5. Thermal insulation board LOGICPIR
6. Vapor barrier VAPORSTOP CA 500
7. Corrugated steel sheet

BALLASTED ROOFING SYSTEM



1. Ballast
2. Geotextile 300 g/m²
3. PVC membrane LOGICROOF V-GR
4. Thermal insulation board LOGICPIR
5. Thermal insulation board LOGICPIR Slope
6. Thermal insulation board LOGICPIR
7. Vapor barrier VAPORSTOP CA 500
8. Reinforced concrete base



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